

A

B

C

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## ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.

Assembly shall conform with RoHS Directive 2011/65/EU.

Components shall be placed according to the associated CPL and BOM documents.

Lead-free SAC305 solder shall be used.

Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.

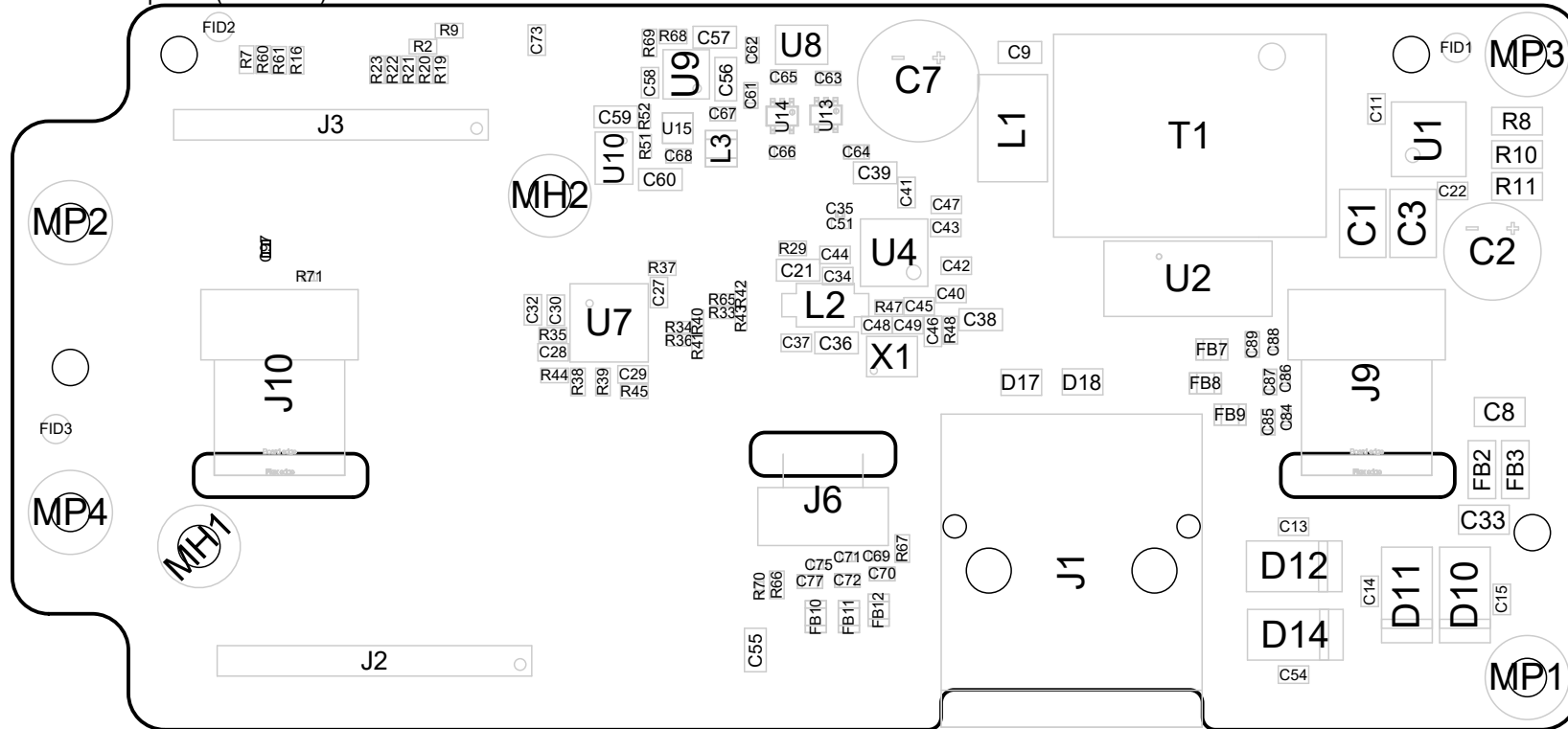
BGA components shall be 100% checked with x-ray for solder bridges after reflow.

Finished assemblies shall be removed from panel prior to delivery.

Notes:

1

View from Top side (Scale 2:1)



Title: SJ2088POE

Number: D2088000

Revision: =revision

Date: 21/04/2021

Sheet: 1 of 2

Drawn by: Brian Weinstein / Sandesh Joshi

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A

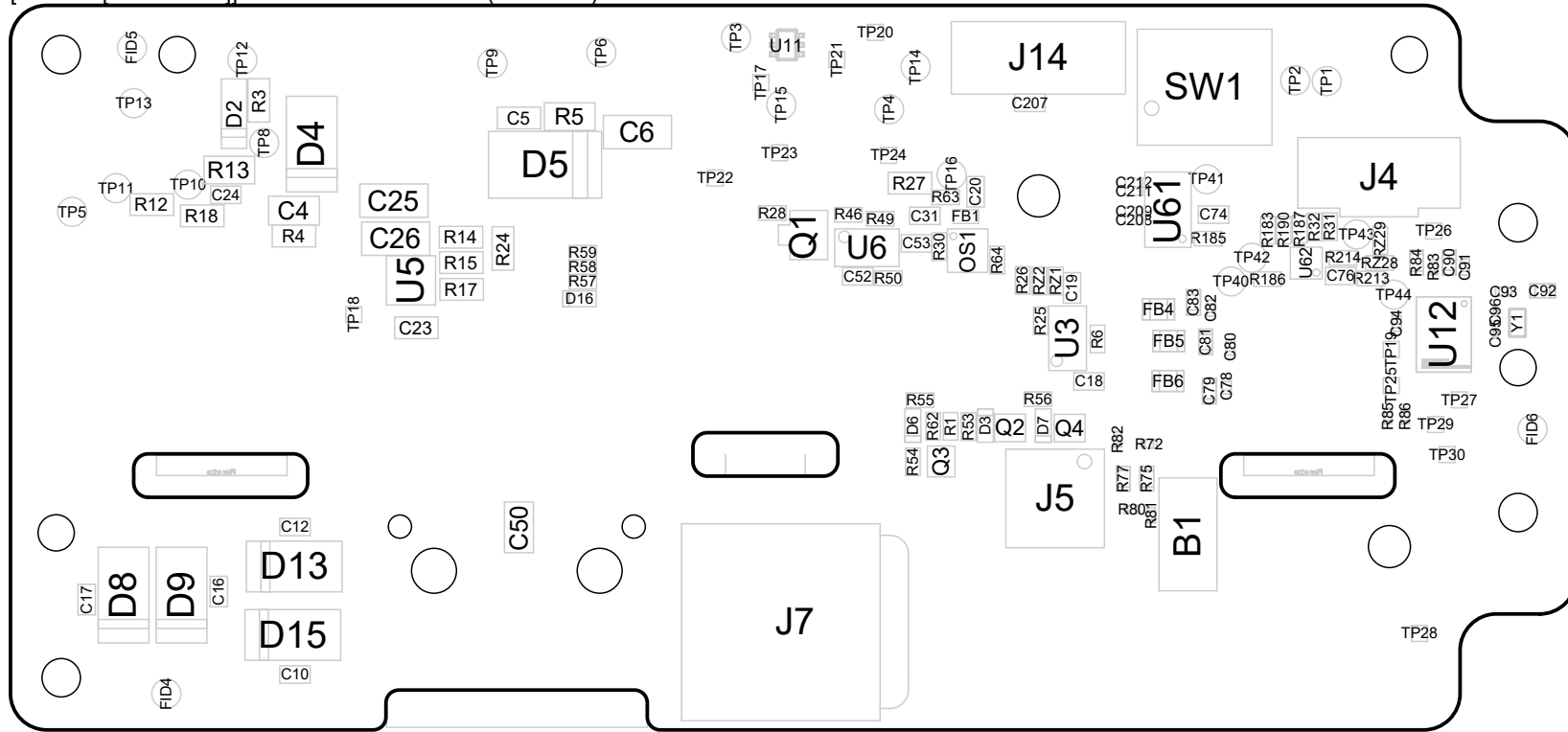
B


C

D

E

[Variant: [All Variants]]: View from Bottom side (Scale 2:1)



Title: <b>SJ2088POE</b>		
Number: D2088000	Revision: =revision on	
Date: 21/04/2021	Sheet: 2 of 2	PROPRIETARY AND CONFIDENTIAL
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